

## APFA2507LSURKSYKZGKC

2.5 x 0.7 mm Right Angle SMD Chip LED Lamp

# 

## **DESCRIPTIONS**

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- . It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

## **FEATURES**

- 2.5 x 1.0 x 0.7 mm right angle SMD LED, 0.7 mm thickness
- · Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 3000 pcs / reel
- Moisture sensitivity level: 3
- · Tinned pads for improved solderability
- Halogen-free
- RoHS compliant

## **APPLICATIONS**

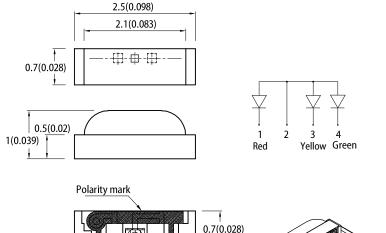
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

## **ATTENTION**

Observe precautions for handling electrostatic discharge sensitive devices



## **PACKAGE DIMENSIONS**



0.35(0.014)

0.3(0.012)

0.35(0.014)

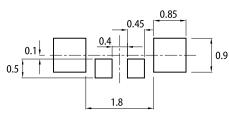
# RECOMMENDED SOLDERING PATTERN

0.3(0.012)

0.35(0.014)

0.35(0.014)

(units: mm; tolerance: ± 0.1)



- Toles.

  1. All dimensions are in millimeters (inches).

  2. Tolerance is ±0.15(0.006") unless otherwise noted.

  3. The specifications, characteristics and technical data described in the datasheet are subject to
- The specifications, characteristics and technical data described in the datastreet are subject to change without prior notice.

  The device has a single mounting surface. The device must be mounted according to the specifications. For right angle SMD LEDs, the solder stencil should be at least 5mil in thickness, to prevent poor solder wetting

#### **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 2mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
APFA2507LSURKSYKZGKC	■ Hyper Red (AlGaInP)	Water Clear	20	30		
			*6	*10		
	Super Bright Yellow (AlGaInP)		6	15	4000	
			*6	*15	130°	
	Green (InGaN)		50	100		
			*50	*100		

Notes.

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

\* Luminous intensity value is traceable to CIE127-2007 standards.



## ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Parameter	Symbol	Emitting Color	Тур.	Max.	
Wavelength at Peak Emission I <sub>F</sub> = 2mA	$\lambda_{peak}$	Hyper Red Super Bright Yellow Green	645 590 515	-	nm
Dominant Wavelength I <sub>F</sub> = 2mA	$\lambda_{dom}$ [1]	Hyper Red Super Bright Yellow Green	630 590 525	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 2mA	Δλ	Hyper Red Super Bright Yellow Green	28 20 35	-	nm
Capacitance	С	Hyper Red Super Bright Yellow Green	35 20 45	-	pF
Forward Voltage I <sub>F</sub> = 2mA	V <sub>F</sub> <sup>[2]</sup>	Hyper Red Super Bright Yellow Green	1.75 1.85 2.65	2.2 2.2 3.1	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Hyper Red Super Bright Yellow Green	-	10 10 50	μА
Temperature Coefficient of $\lambda_{peak}$ I <sub>F</sub> = 2mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambdapeak}$	Hyper Red Super Bright Yellow Green	0.14 0.12 0.05	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 2mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambdadom}$	Hyper Red Super Bright Yellow Green	0.05 0.07 0.03	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 2mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Hyper Red Super Bright Yellow Green	-1.9 -1.9 -3.0	-	mV/°C

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## ABSOLUTE MAXIMUM RATINGS at $T_A$ =25°C

Barrantan	Symbol	Value			1124
Parameter		Hyper Red	Super Bright Yellow	Green	Unit
Power Dissipation	$P_D$	75	75	102.5	mW
Reverse Voltage	V <sub>R</sub>	5	5	5	V
Junction Temperature	T <sub>j</sub>	115	115	115	°C
Operating Temperature T <sub>op</sub> -40 to +85				°C	
Storage Temperature T <sub>stg</sub> -40 to +85				°C	
DC Forward Current	I <sub>F</sub>	30	30	25	mA
Peak Forward Current	I <sub>FP</sub> <sup>[1]</sup>	185	175	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	3000	450	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	480	770	490	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	350	660	370	°C/W

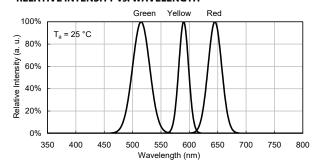
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2.  $R_{\text{Ib.Ja}}$ ,  $R_{\text{Rb.Ja}}$ ,  $R_{\text{Bulls}}$  from mounting on PC board FR4 (pad size  $\geq$  16 mm<sup>2</sup> per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

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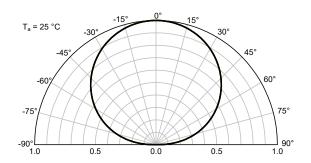


## **TECHNICAL DATA**

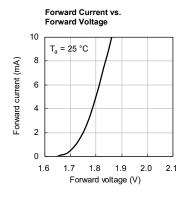
## **RELATIVE INTENSITY vs. WAVELENGTH**

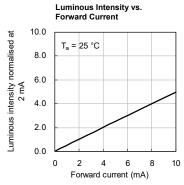


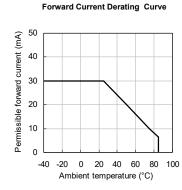
#### **SPATIAL DISTRIBUTION**

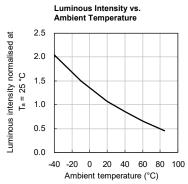


## **HYPER RED**

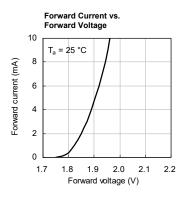


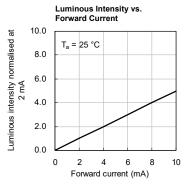


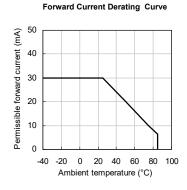


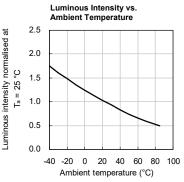


## **SUPER BRIGHT YELLOW**



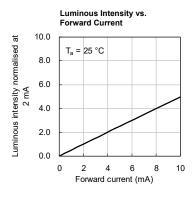


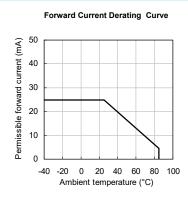


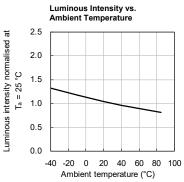


## **GREEN**

Forward Current vs. Forward Voltage T<sub>a</sub> = 25 °C 8 Forward current (mA) 6 4 2 2.5 27 29 3 1 3.3 Forward voltage (V)

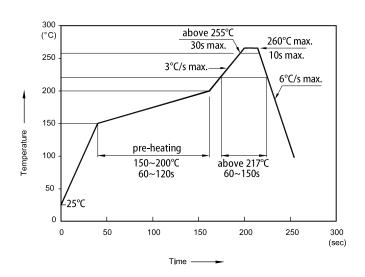




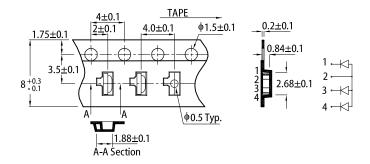




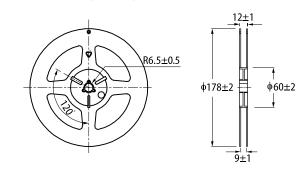
#### REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



## TAPE SPECIFICATIONS (units:mm)



## **REEL DIMENSION** (units: mm)



#### Notes

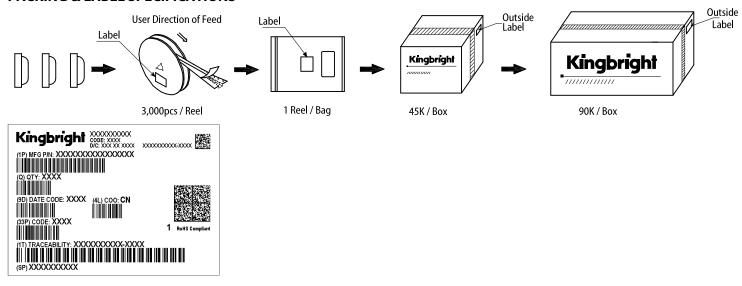
- Notes.

  1. Don't cause stress to the LEDs while it is exposed to high temperature.

  2. The maximum number of reflow soldering passes is 2 times.

  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

## **PACKING & LABEL SPECIFICATIONS**



## **PRECAUTIONARY NOTES**

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.

  The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

  The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
- liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.

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